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APPLICANTS

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** CONTINUING DATA ***** now K.N.

** FOREIGN APPLICATIONS ***** yes K.N.

JAPAN 2003-110125 04/15/2003

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

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Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	STATE OR	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance	COUNTRY	DRAWING	CLAIMS	CLAIMS
Verified and Acknowledged	<i>1/26/2004</i> <i>K.N.</i> Examiner's Signature Initials	JAPAN	2	7	2

ADDRESS

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TITLE

Solder deposition method and solder bump forming method

FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time)
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